



The following is a new Micron Part Change Notification. If you have questions regarding this email, please contact your sales representative, field support team or use the information request button in this email.

Use the buttons below to indicate your response to this PCN.

Approve Micron is authorized to ship this product on the stated schedule.	Request Information Request additional information prior to approving the change.	Not Applicable This change is not applicable to you.
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Assembly Conversion from Ablebond 2025M Epoxy to HR900T DAF on DRAM BGA Single Die Package (SDP)

PCN: 31706

Published: 2015-11-12

Type:	Material Change - Product
Description:	DRAM SDP BGA packages currently using 2025M epoxy die attach adhesive will be converted to HR900T die attach film material.

Reason:	Manufacturing Efficiency, Supply Flexibility/Security
Product Affected:	DRAM SDP BGA package assembled in Micron Singapore site for the following products: DDR 256Mb 50nm (T66A) and SDR

64, 128, 256Mb 50nm (Y64A, Y65A, Y66A)

Affected Micron Part Number **Recommended Replacement** **Customer Part Number**

Component

MT46V16M16CY-5B AAT:M		
MT46V16M16CY-5B AIT:M		
MT46V16M16CY-5B IT:M		557-1598-ND
MT46V16M16CY-5B XIT:M		
MT46V16M16CY-5B:M		
MT46V32M8CY-5B:M		
MT48LC16M16A2B4-6A AAT:G		
MT48LC16M16A2B4-6A AIT:G		
MT48LC16M16A2B4-6A IT:G		
MT48LC16M16A2B4-6A XIT:G		
MT48LC16M16A2B4-6A:G		MT48LC16M16A2B4-6A:G-ND
MT48LC16M16A2B4-7E IT:G		
MT48LC16M16A2B4-7E:G		
MT48LC16M8A2BB-6A AAT:L		
MT48LC16M8A2BB-6A AIT:L		
MT48LC16M8A2BB-6A XIT:L		
MT48LC16M8A2BB-6A:L		
MT48LC2M32B2B5-6A AAT:J		
MT48LC2M32B2B5-6A AIT:J		
MT48LC2M32B2B5-6A IT:J		
MT48LC2M32B2B5-6A:J		
MT48LC32M8A2BB-6A:G		
MT48LC32M8A2BB-7E:G		
MT48LC4M16A2B4-6A IT:J		
MT48LC4M16A2B4-6A:J		
MT48LC4M16A2B4-7E:J		

MT48LC4M32B2B5-6A AAT:L		
MT48LC4M32B2B5-6A AIT:L		
MT48LC4M32B2B5-6A IT:L		
MT48LC4M32B2B5-6A XIT:L		
MT48LC4M32B2B5-6A:L		MT48LC4M32B2B5-6A:L- ND
MT48LC64M4A2BB-6A:G		
MT48LC64M4A2BB-7E:G		
MT48LC8M16A2B4-6A AAT:L		
MT48LC8M16A2B4-6A AIT:L		
MT48LC8M16A2B4-6A IT:L		
MT48LC8M16A2B4-6A XIT:L		

*Materials that have been ordered are in **bold**.

Method of Identification:	Cross sections would show a slight difference in color of the die attach material and the film material eliminates the fillets at the edges of the die (only seen in cross sections).
Micron Sites Affected:	MSB – Singapore
Qualification Plan:	Product converted to HR900T die attach film material will be qualified according to Company qualification procedure and best practices. Qualification plan will be available upon request.
Sample Available:	2016-01-07
Qual Data Available:	2016-01-29
Product Ship Date:	2016-04-29

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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Thank you

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